

# Product and Process Change Notice

<b>PCN No.</b>	PCN03033	<b>PCN Date</b>	4/19/2021	<b>Effective Date</b>	5/21/2021
<b>Title</b>	Mold Compound Die Attach Change for 1Mb (x16), 2Mb (x16) and 4Mb (x8 and x16) BGA Package from OSE				

Everspin is changing the mold compound, BLT1 die attach material, and BLT2 die attach material for 1Mb (x16) and 4Mb (x8 and x16) BGA Package from OSE. 30 day effective due to increased demand on part numbers listed below.

### Reason For Change

Increased product demand. Improved manufacturing efficiency and capacity at assembly site.

### Affected Products

Part Number	Description	Part Number	Description
MR2A16AMA35	Commercial Temp.	MR2A16AMA35	Commercial Temp., T&R
MR2A16ACMA35	Industrial Temp.	MR2A16ACMA35R	Industrial Temp., T&R
MR2A16AVMA35	Extended Temp.	MR2A16AVMA35R	Extended Temp., T&R
MR2A08AMA35	Commercial Temp.	MR2A08AMA35R	Commercial Temp., T&R
MR2A08ACMA35	Industrial Temp.	MR2A08ACMA35R	Industrial Temp., T&R
MR1A16AMA35	Commercial Temp.	MR1A16AMA35R	Commercial Temp., T&R
MR1A16ACMA35	Industrial Temp.	MR1A16ACMA35R	Industrial Temp., T&R
MR1A16AVMA35	Extended Temp.	MR1A16AVMA35R	Extended Temp., T&R
MR0A16AMA35	Commercial Temp.	MR0A16AMA35R	Commercial Temp., T&R
MR0A16ACMA35	Industrial Temp.	MR0A16ACMA35R	Industrial Temp., T&R
MR0A16AVMA35	Extended Temp.	MR0A16AVMA35R	Extended Temp., T&R

### Impact on Form, Fit, Function, Quality or Reliability

No impact

### Proposed First Ship Date for Change:

May 21, 2021

### Key Material Differences

Material	Old	New
Mold Compound	Kyocera G1250	Sumitomo G760LB
BLT1 Die Attach	Hitachi HR-5104 DAF	Nitto EM-760 DAF
BLT2 Die Attach	Nitto EM-310VJ DAF	Sumitomo CRM-1150B Epoxy

### Product Identifier

Assembly site code = S for OSE Taiwan

### Supplier Qual Plan Schedule and Results

Mold Compound and Die attach material change qualification is complete and all Everspin requirements met; a qualification report is available on request.

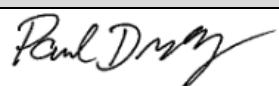


### Date Qualification Samples Are Available:

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

# Product and Process Change Notice

<b>PCN No.</b>	PCN03033	<b>PCN Date</b>	4/19/2021	<b>Effective Date</b>	5/21/2021
<b>Title</b>	Mold Compound Die Attach Change for 1Mb (x16), 2Mb (x16) and 4Mb (x8 and x16) BGA Package from OSE				

**Acceptance of Change**  
 Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

Contact Information	Sample Information	<input checked="" type="checkbox"/> Samples Available Now
Product Marketing Everspin Technologies (480) 347-1111	Contact Everspin sales: <a href="http://www.everspin.com/contact-us-everspin-technologies">http://www.everspin.com/contact-us-everspin-technologies</a> If using the on-line sample request please refer to this PCN # to receive samples.	
<b>Originator</b>		
<u>Date</u> 4/19/2021	<u>Title</u> Senior Quality Engineer	<u>Name</u> Paul Drobny 
<b>Approval and Release</b>		
<u>Date</u> 4/19/2021	<u>Title</u> Director of Fab Ops & Quality	<u>Name</u> Khaldoun Barakat 
<u>Date</u> 4/19/2021	<u>Title</u> VP of Operations	<u>Name</u> Norm Armour 
<u>Date</u> 4/19/2021	<u>Title</u> VP of Sales & Marketing	<u>Name</u> Troy Winslow 